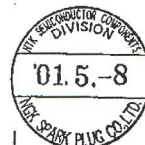


- NOTES: 1. GOLD PLATE 100μ INCHES MIN OVER $80\sim 350\mu$ INCHES NICKEL.
 2. GND PAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD. SEAL RING ISOLATED.
 3. ASI SPECIFICATION MEM46010 SHALL APPLY.
 4. ELECTRICAL REQUIREMENTS.

	NO.14,28	OTHERS
CAPACITANCE		2.5pF MAX
	NO.1,14,28	OTHERS
INDUCTANCE (1MHz)	5nH MAX	10nH MAX

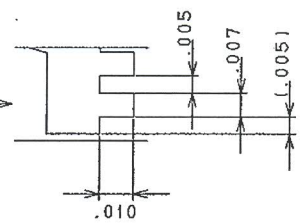
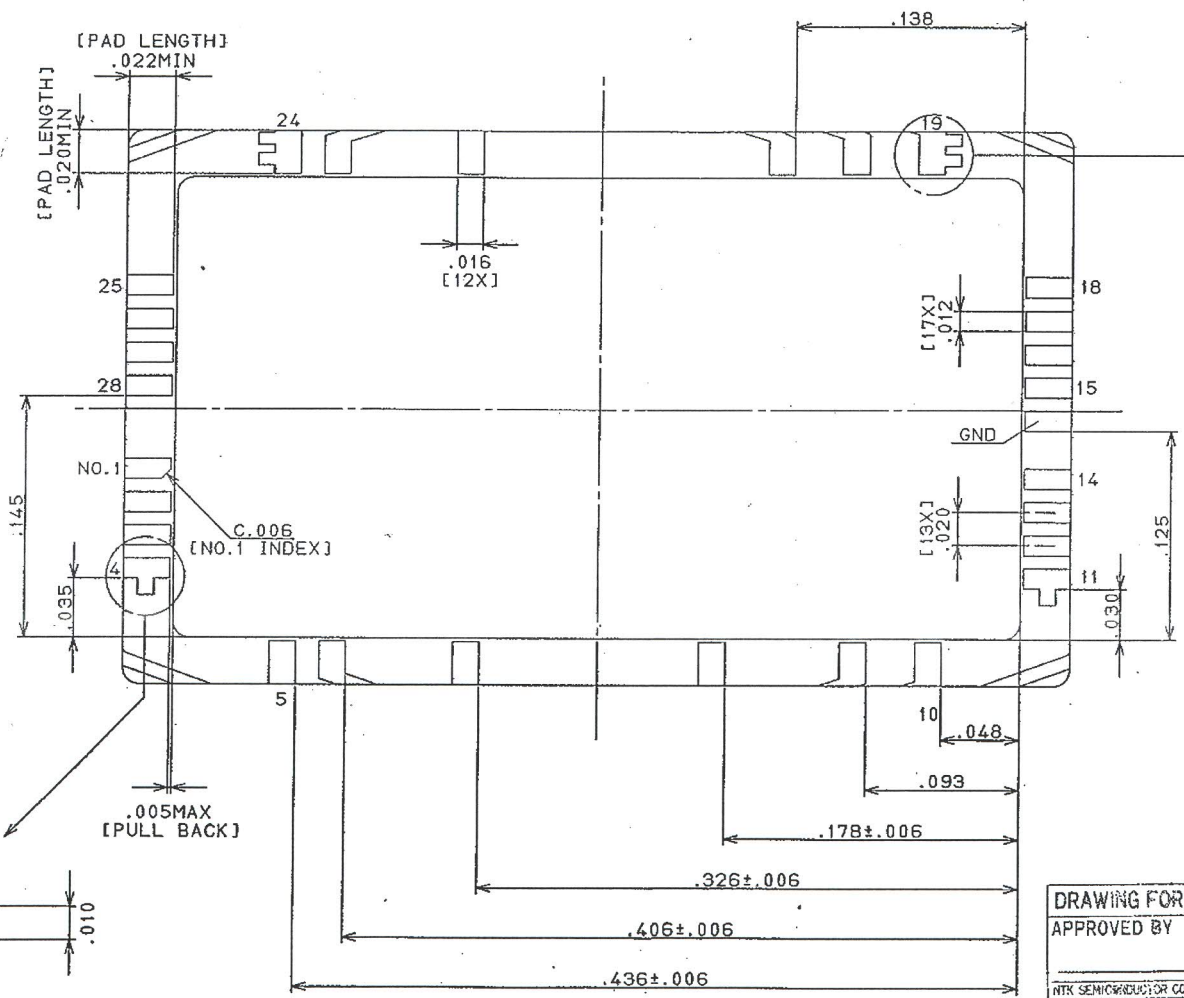
5. OR SHALL BE ALLOWED.

DRAWING FOR APPROVAL
 APPROVED BY
 NTK BEARING/PRODUCOR COMPONENTS DIVISION

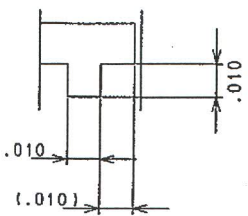


③					
②					
①	CERAMIC	BLACK ALUMINA		NEW DRAWING	MAY-08-2001
Item Name	Material	Description	Rev.	Description	Date
UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1% N. L. T. 2 DECIMALS .XX ± 01 3 DECIMALS .XXX ± .005			DRAWN	T. ITOU	NTK TECHNICAL CERAMICS
CUSTOMER	ASI	CHECKED	S. MAEHARA	TITLE	NGK SPARK PLUG CO., LTD
DWG NO.		APPROVED	<i>Maehara</i>	DWG NO.	28 LEAD CHIP CARRIER
		UNIT	INCH	SCALE	1:2
					SIZE (G)
					IRK28F1-5624C

MODIFIED DWG NO.



NOTE:5



.005MAX
[PULL BACK]

DRAWING FOR APPROVAL
APPROVED BY
NTK SEMICONDUCTOR COMPONENTS DIVISION



B/G PADS DETAIL

Rev.	Description	Date
φ	NEW DRAWING	MAY-08 -2001

UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1% N. L. T. 2 DECIMALS. XX ± .01 3 DECIMALS. XXX ± .005		DRAWN T. ITOU	NTK TECHNICAL CERAMICS NGK SPARK PLUG CO., LTD.
CUSTOMER ASI	APPROVED S. MAEHARA	TITLE B/G PADS DETAIL	
DWG NO.	UNIT INCH	SCALE /	DWG NO. IRK28F1-5624C

MODIFIED DWG NO.	1	2	3	4	5	6	7	8
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